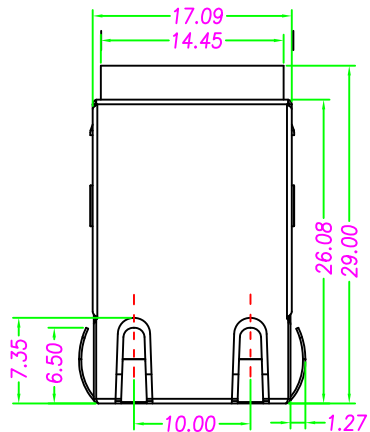
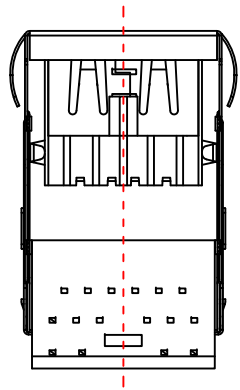
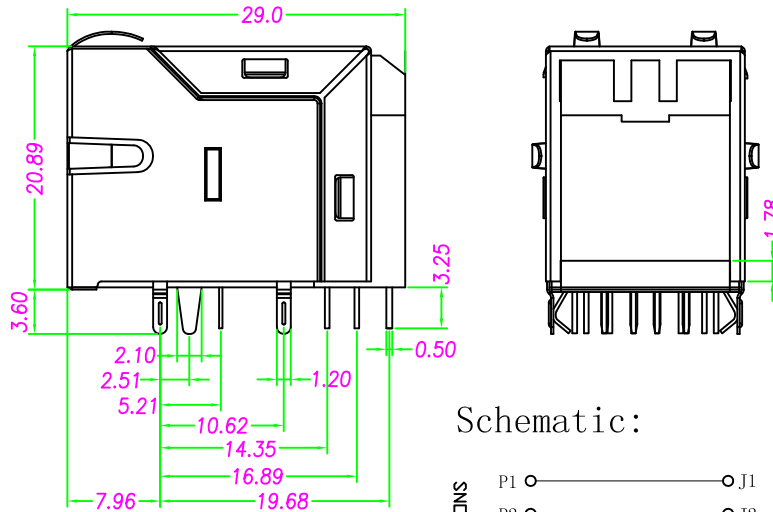
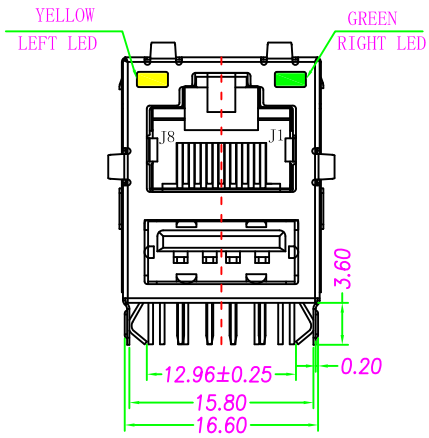
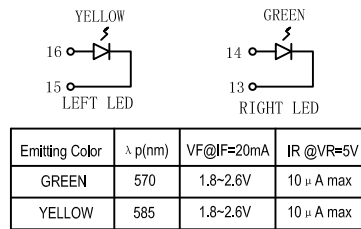
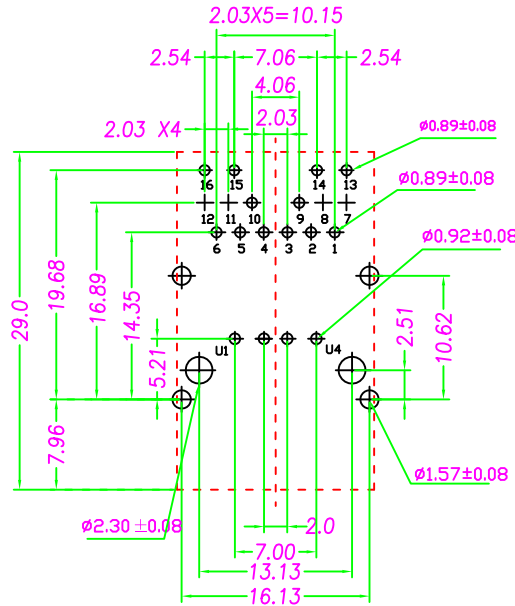
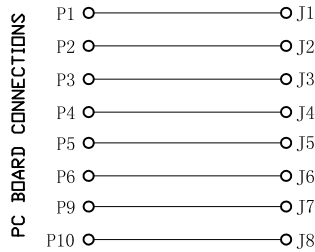


Mechanical:



Schematic:



SUGGESTED PCB LAYOUT (TOP VIEW)

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2013/10/29	

NOTES:Electrical:

1. Voltage:125VAC RMS.
2. Current Rating:1.5A.
3. Contact Resistance:30 Milliohms max.
4. Insulation Resistance:500 Megohms Min @500VDC.
5. Dielectric Strength:1000VAC RMS 50Hz 1Min.
6. RJ-45 Contact plating: Gold 6 micro-inches min.
In contact area
USB Contact plating: Gold flash
7. Gold Plating: Gold Flash
8. Wave solder temperture: 230°C to 250°C, 5~10 Sec.

MECHANICAL:

1. Housing Material:Glass Filled Polyester UL94V-0.
 2. Contact Material:Phosphor Bronze φ 0.45mm.
 3. Plating:Gold Plating Over Nickel.
 4. Operating:750 Cycles Min.
 5. Shield 0.23mm Thickness Copper Alloy With Nickel Plated.
 6. PCB Retention Pre-Solder:1 LB Min.
- Environmental:
1. Temperature Range:-45°C ~ +85°C.
 2. Relative Humidity:90~95% (40±2°C)

PART NO: LPJE306XAGNL

- Gold Plated
- 0: Gold Flash
- 1: 1.5u"
- 2: 3u"
- 3: 6u"
- 4: 15u"
- 5: 30u"
- 6: 50u"



X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX ±0.25	CHKD:	
X:XXX ±0.05	DR: TOM	TITLE: RJ45/Single USB Jack
ANGLES ±1°	UNIT: mm	PART NO.: LPJE3060AGNL
	SCALE: 2/1	SHEET: 1/1
	REV: A	DWG NO.: LP13102911